

Title (en)
HEAT INSULATOR AND FASTENING STRUCTURE FOR SAME

Title (de)
WÄRMEISOLATOR UND BEFESTIGUNGSSTRUKTUR DAFÜR

Title (fr)
ISOLANT THERMIQUE ET SA STRUCTURE DE FIXATION

Publication
EP 3001005 A4 20160518 (EN)

Application
EP 14800794 A 20140519

Priority
• JP 2013107282 A 20130521
• JP 2014063204 W 20140519

Abstract (en)
[origin: EP3001005A1] A heat insulator fastening structure comprises: a heat insulator (1) which is configured so as to cover an exhaust manifold (2); and fasteners (3) which are configured so as to fasten the heat insulator (1) to an object to which the heat insulator (1) is to be fastened, the heat insulator (1) being fastened so as to be displaceable in a predetermined range. The heat insulator (1) has: a single first region (A1) which is configured so as to vibrate in the same phase; and a single second region (A2) which is different from the first region (A1) and which is configured so as to vibrate in the same phase. At least one of the fasteners (3) fastens the first region (A1) to the object to which the heat insulator (1) is to be fastened. At least another one of the fasteners (3) fastens the second region (A2) to the object to which the heat insulator (1) is to be fastened.

IPC 8 full level
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F01N 2260/08 (2013.01 - EP US); **F01N 2450/24** (2013.01 - EP US)

Citation (search report)
• [X1] WO 2011021495 A1 20110224 - SANWA PACKING INDUSTRY CO LTD [JP], et al
• [X1] US 2009000861 A1 20090101 - HIKAMI TAKAYUKI [JP]
• See references of WO 2014189000A1

Designated contracting state (EPC)
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BA ME

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EP 3001005 A1 20160330; EP 3001005 A4 20160518; CN 105264194 A 20160120; JP 2014227887 A 20141208; JP 5885258 B2 20160315;
US 2016102929 A1 20160414; WO 2014189000 A1 20141127

DOCDB simple family (application)
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